



BGA REBALLER

We know how frustrating it is to remove a component knowing that it is still good, but not being able to use it again! That's why STI Electronics developed a unique and simple device called the **BGA Reballer**. The Reballing system allows you to remove the existing spheres from the component and re-establish the spheres on the Ball Grid Array component. Therefore, you are able to reuse your components ... **saving you money!**

Here are the simple steps to reball your components:

1. Using your soldering iron, remove the excess solder and spheres
2. Apply the flux
3. Insert the component into the **Reballer** fixture
4. Pour in the spheres from the kit
5. Drain off the extra spheres
6. Heat the fixture and component to attach the spheres

The **Reballer** is so simple to use and very cost effective! For only £250 you receive the reballer fixture, 10,000 spheres of the correct size for your component, flux, tweezers and a brush. Each **Reballer** is designed to exactly fit a BGA package so that the spheres can be placed correctly each time. The **Reballer** is also available for chip scale and flash memory devices.

